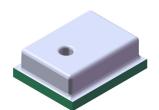


XGZP6816D BAROMETRIC PRESSURE SENSOR

FEATURES

- Wide Ranges: 300 ... 1100hPa
- <u>1.8V ~ 3.6V</u> Power Supply
- Absolute Pressure Type
- Current Consumption:<80uA(single measurement at 128 OSR)
- Standby Current:<100nA (25°C)
- Calibrated Digital Signal(I2C Interface)
- Absolute Pressure Accuracy:±1hPa(8.3m)
- Relative Pressure Accuracy: ±0.12hPa(1m)
- Temperature Accuracy:±1°C



APPLICATIONS

- Enhancement of GPS navigation (dead-reckoning, slope detection, etc.)
- In- and out-door navigation
- Leisure and sports
- Weather forecast
- Vertical velocity indication (rise/sink speed)

INTRODUCTION

XGZP6816D is a perfect silicon pressure sensor offering a ratiometric I2C interface for reading pressure over the specified full scale pressure span.

The XGZP6816D is a miniaturized Digital Barometric Air Pressure Sensor with a high accuracy and a low current consumption. The XGZP6816D is both a pressure and a temperature sensor. The pressure sensor element is based on a capacitive sensing principle which guarantees a high precision during temperature changes. The small package makes the XGZP6816D ideal for mobile applications and wearable devices.

The XGZP6816D's internal signal processor converts the output from the pressure and temperature sensor elements to 24-bit results. Each pressure sensor has been calibrated individually and contains calibration coefficients. The coefficients are used in the application to convert the measurement results to true pressure and temperature values.

XGZP6816D pressure sensor is for high volume application at an affordable cost but perfect performance.



PERFORMANCE PARAMETER

Unless otherwise specified, measurements were taken with a a temperature of $25\pm1^{\circ}$ C and humidity from $25\% \sim 85\%$ RH.

| Parameter | Conditions | Min | Тур | Max | Units |
|----------------------------|----------------------|-------|-----|------|-------|
| Temp.Measure Range | Interior temp.sensor | -40 | | 150 | ℃ |
| Absolute Pressure Accuracy | | -1 | | 1 | hPa |
| Relative Pressure Accuracy | | -0.12 | | 0.12 | hPa |
| Temp. Measure Accuracy | | -1 | | 1 | ℃ |
| Over Pressure | | | 2x | | Rated |
| Working Temp. | | -40 | | 85 | ℃ |
| CompensatedTemp. | | 0 | | 60 | ℃ |

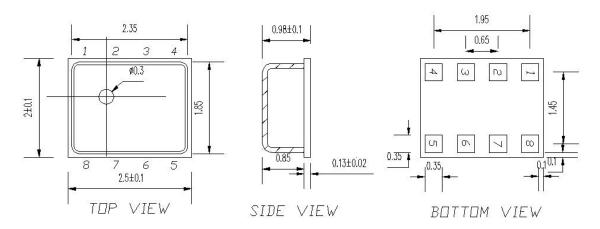
ELECTRICAL CHARACTERISTICS(ASIC)

| Parameter | Conditions | | Min | Тур | Max | Units |
|--------------------------------|--|------------------------|-----|-------|------|-------|
| | At VDD=2V | | 32 | | | dB |
| | | Oversampling rate 128x | | 80 | | |
| | | Oversampling rate 64x | | 42 | | |
| | 0.00 | Oversampling rate 32x | | 23 | | _ |
| Average current during 1Hz | OSR_P | Oversampling rate 16x | | 13 | | μΑ |
| conversion rate measurement | | Oversampling rate 8x | | 8 | | |
| | | Oversampling rate 3x | | 6 | | |
| | | Oversampling rate 2x | | 4 | | |
| Peak Current | | | | 0.3 | | mA |
| Standby Current | Standby current in sleep state at 25°C | | | 50 | 250 | nA |
| | | Oversampling rate 128x | | 203 | | |
| Single measurement time | | Oversampling rate 64x | | 105 | | |
| (Including external bridge and | 000.0 | Oversampling rate 32x | | 56 | | |
| the OSR of temperature | OSR_P | Oversampling rate 16x | | 31 | | ms |
| measurement is 1024x) | | Oversampling rate 8x | | 19 | | |
| moded of the to 102 thy | | Oversampling rate 4x | | 13 | | |
| | | Oversampling rate 2x | | 10 | | |
| ADC Conversion rate | | OSR as 2x ~ 128x | 20 | | 1350 | Hz |
| I2C Clock frequency | | | | | 3.4 | MHz |
| Temperature resolution | | | | 0.003 | | K/LSB |



| Parameter | Conditions | Min | Тур | Max | Units |
|--------------|--|-----|-----|-----|-------|
| | VDD to the time when the interface communication starts | | | 1 | ms |
| Start Time | VDD to the time when the measurement starts | | | 2.5 | ms |
| | Sleep status to the time when the interface communication starts | | | 0.5 | ms |
| Wake up Time | Sleep status to the time when the measurement starts | | | 2 | 2 |

DIMENSION (Unit:mm)

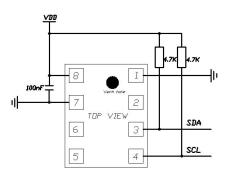


ELECTRIC CONNECTION

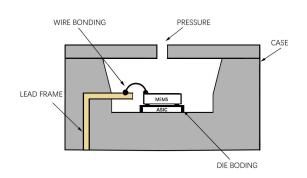
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 |
|-----|----|-----|-----|----|----|-----|-----|
| GND | NC | SDA | SCL | NC | NC | GND | VDD |

| NAME | FUNCTION | |
|------|--|--|
| NC | Do not connect to external circuitry or ground | |
| VDD | Voltage supply | |
| SDA | Data signal(Send& Receive) | |
| SCL | The clock signal | |
| GND | Ground | |

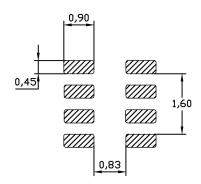
CIRCUIT DIAGRAM



CROSS SECTION



FOOTPRINT(REFERENCE)

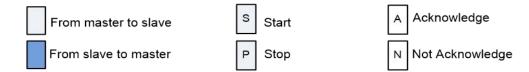




12C INTERFACE

The I2C bus uses SCL and SDA as signal lines, both of which are connected to VDD through pull-up resistors (typically 2.2K) and remain high level when not communicating.

The sensor is calibrated at the factory. Sending the 0xAC command to get the calibrated data..



Write Command



0xF0 means that the default 7bits I2C sensor slave device address is 0x78, and the last 1bit is 0 means that the master device MCU writes to the slave device. 0xAC is the command word to start the slave device sensor to perform a measurement. (The write address is 0X78<<1+0=0XF0, and the read address is 0X78<<1+1=0XF1)

Read Command



After sending the write command, need to wait for a while till measurement finish from the slave device sensor, and then send the read command to read the measurement data. Then sending the 0XF1 command to determine whether the sensor data acquisition has been completed

The waiting time depends on the settings of [13:11] Pressure Oversampling Rate of OTP (Address: 0x14) and [15:14] Temperature Oversampling Rate of OTP (Address: 0x14). The waiting time is =Tp+Tt.

Pressure Oversampling Rate and Measurement Time Comparison Table

| OSR_Pressure[13:11] (Banary) | OSR | Measurement Time Tp(ms) |
|------------------------------|-------|-------------------------|
| 000 | 32768 | 203 |
| 001 | 16384 | 105 |
| 010 | 8192 | 56 |
| 011 | 4096 | 31 |
| 100 | 2048 | 19 |
| 101 | 1024 | 13 |
| 110 | 512 | 10 |

Temperature Oversampling Rate and Measurement Time Comparison Table

| OSR Temperature[15:14] (Banary) | OSR | Measurement Time Tt(ms) |
|---------------------------------|-------|-------------------------|
| 00 | 2048 | 19 |
| 01 | 4096 | 31 |
| 10 | 8192 | 56 |
| 11 | 16384 | 105 |



Read Pressure Value

The read calibration data consists of 6 bytes, which are 1-byte status word, 3-byte pressure calibration value, and 2-byte temperature calibration value.



Table: Status of Bits

| Bit | Significancy | Description | |
|------|------------------|---|--|
| Bit7 | Reserved | Constant 0 | |
| Bit6 | Power indication | .: Power on; 0: Power off | |
| Bit5 | Busy indication | 1: Busy, the device is measuring pressure and temperature and the results are not ready | |
| | | yet. New I2C command will not be proceeded; | |
| | | 0: Idle, the recent I2C command has been executed and the data to be read is ready | |
| Bit4 | Reserved | Constant 0 | |
| Bit3 | Mode Status | NOR mode;1 CMD mode | |
| Bit2 | Memory integrity | 0 Indicates that the OTP memory data integrity test (CRC) passed; | |
| | /error flag | 1 Indicates that the OTP memory data integrity test (CRC) failed。 | |
| | | The data integrity test is only calculated once during the power-on process (POR), so the | |
| | | new CRC value written only can be used after the next POR. | |
| Bit1 | Reserved | Constant 0 | |
| Bit0 | Reserved | Constant 0 | |

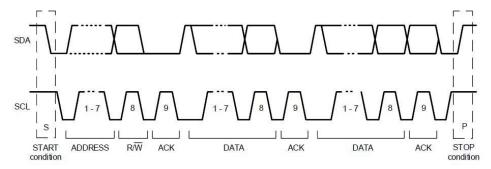
Sleep Standby

After the sensor completes the measurement, it enters the sleep standby state, and the standby power consumption is 0.1uA.

12C TIME DIAGRAM

The I2C interface protocol has special bus signal conditions. Start (S), stop (P) and binary data conditions are shown below. At start condition, SCL is high and SDA has a falling edge. Then the slave address is sent. After the 7 address bits, the direction control bit R/W selects the read or write operation. When a slave device recognizes that it is being addressed, it should acknowledge by pulling SDA low in the ninth SCL (ACK) cycle.

At stop condition, SCL is also high, but SDA has a rising edge. Data must be held stable at SDA when SCL is high. Data can change value at SDA only when SCL is low.





I2C Command

| Command(byte) | Return | Description | NOR Mode | CMD Mode |
|----------------------|------------------------|---|------------|------------|
| 0x00~0x1F | 16-bit data | Read data in the OTP that address matching | Support | Support |
| | | command | | |
| 0x40~0x5F Followed | _ | Write data to OTP; Address is Command value | Support | Support |
| command | | subtract 0x40 (Address is 0x00 to 0x1F) | | |
| byte: 0x0000 ~0xFFFF | | | | |
| 0xA0~0xA7 | 24-bit raw data | Get_Raw | Support | Support |
| Followed command | Get_Raw | Conduct one measurement, and write the raw | | |
| byte: 0xXXXX | | ADC data to registers. See table 6-3 for | | |
| | | further interpretation | | |
| 0xA8 | 24-bit raw data | Start_NOM | No-Support | Support |
| | Get_Raw | Quit CMD mode, enter NOR mode | | |
| 0xA9 | _ | Start_CM | Support | No-Support |
| | | Quit NOR mode, enter CMD mode | | |
| 0xAA | _ | Write_ChecksumC | Support | Support |
| | | If CRC values are not wrote to OTP, the | | |
| | | command check data in OTP register and | | |
| | | writes CRC values to OTP | | |
| 0xAC | 24-bit compensated | Get_Cal | Support | Support |
| | bridge data and 16-bit | Measure based on OTP settings(AZBM, | | |
| | compensated | BM,AZTM and TM), write conpensated bridge | | |
| | temperature data | and temperature data to I2C interface | | |
| 0xB0~0xBF | 24-bit compensated | Get_Cal_S and Get_Cal are the same except | Support | Support |
| | bridge data and 16-bit | that Get_Cal measures based on OTP defined | | |
| | compensated | OSR and Get_Cal_S measures based on | | |
| | temperature data | command defined OSR, see following table | | |

Get_Cal_S Command

| Command 0xBX(HEX) | Function | Detail |
|-------------------|-------------------------|---------------------------|
| X [3] Bit | OSR_T, ADC OSR of | 0: 4x OSR 1: 8x OSR |
| | temperature measurement | |
| X [2:0] Bit | OSR_P, ADC OSR of | 000: 128x OSR 100: 8x OSR |
| | pressure measurement | 001: 64x OSR |
| | | 010: 32x OSR |
| | | 011: 16x OSR 000: 1x OSR |

For example, to set the temperature ADC to 4x oversampling and the piezoelectric panel ADC to 1x oversampling, the command format is 0xB7, Just replace 0xAC with 0xB7



Pressure conversion example:

After reading the calibration data, need to convert simply the unsigned number in the form of AD value..

To facilitate understanding, assuming that the calibration data read is: 0x04, 0x9B, 0xB0, 0xC5.

0x04 is the status, and Bit5 is 1 indicating that the I2C is busy last time, and it needs to wait for a period of time. If Bit5 is 0, it indicates that the device is not busy and data can be read. For a detailed description of each bit of the status word, see above table

The three bytes of 0x9B, 0xB0, and 0xC5 are bridge calibration value.

The pressure calibration value is converted as follows:

Assuming that the range used in this calculation and calibration is 30Kpa-110Kpa, the corresponding AD output is $1677722\sim15099494$ (10%AD $\sim90\%$ AD).

Then convert 0x9B, 0xB0, and 0xC5 into decimal numbers, assuming it is 10203333. According to the formula: pressure_kpa = ((PMAX-PMIN)/(DMAX-DMIN)*(Dtest-DMIN)+PMIN), actual pressure value = (110-30)/(15099494-1677722)*(10203333-1677722)+30=80.816 Kpa

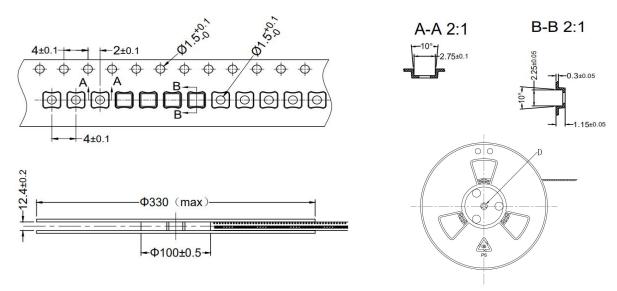
The temperature calibration value is converted as follows:

Converting 0x56, 0xAA to a decimal number is 22186. Since the read calibration data is expressed as a percentage, this percentage is numerically equal to the ratio of the decimal number we converted to the maximum value of 16bits unsigned number (65535, full AD value of whole temperature range from -40°C to 150 °C). Therefore, the following calculations can be made when converting percentages: 22186/65536*100%=33.85%

The temperature calibration range is specified as -40°C — 150°C , so the calibration value=(150-(-40))*33.85%— $40=24.32^{\circ}\text{C}$

PACKING INFORMATION

Tape&Reel(unit: mm)
QTY/reel: 10,000 pcs.





OVERALL NOTES

Unless otherwise specified, following notes are general attention or presentation for all products from CFSensor.

Mounting

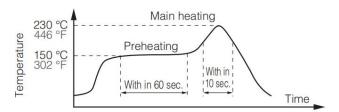
The following steps is for transmitting the air pressure to sensor after sensor soldering on PCB.

- ▼ For some sensors that come with inlet tube, select the flexiable pipe to suit the pressure inlet that is firm enough to prevent the pressure leaks.
- ▼ Atmosphere hole (for Gauge type sensors) and Inlet pipe/hole can't be blocked with gel or glue etc,...
- ▼ Avoiding excessive external force operation

Soldering

Due to its small size, the thermal capacity of the pressure sensor is low. Therefore, take steps to minimize the effects of external heat. Damage and changes to characteristics may occur due to heat deformation. Use a non-corrosive resin type of flux. Since the pressure sensor is exposed to the atmosphere, do not allow flux to enter inside.

- ▼ Manual soldering
- © Raise the temperature of the soldering tip between 260 and 300°C/500 and 572°F (30 W) and solder within 5 seconds.
- ⊙The sensor output may vary if the load is applied on the terminal during soldering.
- ⊙ Keep the soldering tip clean.
- **▼**DIP soldering (DIP Terminal)
- ⊙ Keep the temperature of the DIP solder tank below 260°C/500 and solder within 5 seconds.
- ⊙To avoid heat deformation, do not perform DIP soldering when mounting on the PCB which has a small thermal capacity.
- ▼ Reflow soldering (SMD Terminal)
- ⊙The recommended reflow temperature profile conditions are given below.



- ⊙ Self alignment may not always work as expected, therefore, please carefully note the position of the terminals and pattern.
- ⊙The temperature of the profile is assumed to be a value measured with the PCB of the terminal neighborhood.
- Please evaluate solderbility under the actual mounting conditions since welding and deformation of the pressure inlet port may occur due to heat stress depending on equipments or conditions.
- ▼ Rework soldering
- ⊙Complete rework at a time.
- Ouse a flattened soldering tip when performing rework on the solder bridge. Do not add the flux.
- ⊙ Keep the soldering tip below the temperature described in the specifications.
- ▼ Avoid drop and rough handling as excessive force may deform the terminal and damage soldering characteristics.
- ▼ Keep the circuit board warpage within 0.05 mm of the full width of the sensor.
- ▼ After soldering, do not apply stress on the soldered part when cutting or bending the circuit board.
- ▼ Prevent human hands or metal pieces from contacting with the sensor terminal. Such contact may cause anomalous outlets as the terminal is exposed to the atmosphere.
- ▼ After soldering, prevent chemical agents from adhering to the sensor when applying coating to avoid insulation deterioration of the circuit board.



Connecting

- ▼ Correctly wire as in the connection diagram. Reverse connection may damage the product and degrade the performance.
- ▼ Do not use idle terminals(N/C) to prevent damages to the sensor.

Cleaning

- ▼ Since the pressure sensor is exposed to the atmosphere, do not allow cleaning fluid to enter inside from atmosphere hole (for Gauge type sensors) and inlet pipe.
- Avoid ultrasonic cleaning since this may cause breaks or disconnections in the wiring.

Environment

- ▼ Please avoid using or storing the pressure sensor in a place exposed to corrosive gases (such as the gases given off by organic solvents, sulfurous acid gas, hydrogen sulfides, etc.) which will adversely affect the performance of the pressure sensor chip.
- ▼ Since this pressure sensor itself does not have a water-proof construction (even available media can be liquid), please do not use the sensor in a location where it may be sprayed with water, etc.
- ▼ Avoid using the pressure sensors in an environment where condensation may form. Furthermore, its output may fluctuate if any moisture adhering to it freezes.
- ▼ The pressure sensor is constructed in such a way that its output will fluctuate when it is exposed to light. Especially when pressure is to be applied by means of a transparent tube, take steps to prevent the pressure sensor chip from being exposed to light.
- ▼ Avoid using pressure sensor where it will be susceptible to ultrasonic or other high-frequency vibration.
- ▼ Keeping the sensors sealed in static shielding bags with an oxygen-free condition and use the sensor as soon as possible once unfold the package, because the sensors' PINs may be oxidated a bit under atmosphere environment(slight oxidation wouldn't affect soldering and performance)

More Precautions

- ▼That using the wrong pressure range or mounting method may result in accidents.
- ▼ The only direct pressure medium you can use is non-corrosive gas or air as illuminated above(Note: some sensors are compatible with liquid media). The use of other media, in particular, corrosive gases and liquid (organic solvent based, sulfurous acid based, and hydrogen sulfide based, etc.) or contains foreign substances will cause malfunction and damage. Please do not use them and check with CFSensor.
- ▼The pressure sensor is positioned inside the pressure inlet. Never poke wires or other foreign matter through the pressure inlet since they may damage the sensor or block the inlet. Avoid use when the atmospheric pressure inlet(only for Gauge type pressure sensor) is blocked.
- ▼ Use an operating pressure which is within the rated pressure range. Using a pressure beyond this range may cause damage.
- ▼ Since static charge can damage the pressure sensor, bear in mind the following handling precautions.
- ①When storing the pressure sensor, use a conductive material to short the pins or wrap the entire sensor in aluminum foil. Common plastic containers should not be used to store or transport the sensor since they readily become charged.
- When using the pressure sensor, all the charged articles on the bench surface and the work personnel should be grounded so that any ambient static will be safely discharged.



▼ Based on the pressure involved, give due consideration to the securing of the pressure sensor.

[SAFETY NOTES]

Using these sensors products may malfunction due to external interference and surges, therefore, please confirm the performance and quality in actual use. Just in case, please make a safety design on the device (fuse, circuit breaker, such as the installation of protection circuits, multiple devices, etc.), so it would not harm life, body, property, etc even a malfunction occurs. To prevent injuries and accidents, please be sure to observe the following items:

- The driving current and voltage should be used below the rated value.
- Please follow the terminal connection diagram for wiring. Especially for the reverse connection of the power supply, it will cause an accident due to circuit damage such as heat, smoke, fire, etc.
- In order to ensure safety, especially for important uses, please be sure to consider double safety circuit configuration.
- Do not apply pressure above the maximum applied pressure. In addition, please be careful not to mix foreign matter into the pressure medium. Otherwise, the sensor will be discarded, or the media will blew out and cause an accident.
- Be careful when fixing the product and connecting the pressure inlet. Otherwise, accidents may occur due to sensor scattering and the blowing out of the media.
- If the sensor come with sharp PIN, please be careful not to hurt your body when using it.

[WARRANTY]

The information in this sheet has been carefully reviewed and is believed to be accurate; however, no responsibility is assumed for inaccuracies. Furthermore, this information does not convey to the purchaser of such devices any license under the patent rights to the manufacturer. CFSensor reserves the right to make changes without further notice to any product herein. CFSensor makes no warranty, representation or guarantee regarding the suitability of its product for any particular purpose, nor does CFSensor assume any liability arising out of the application or use of any product or circuit and specifically disclaims any and all liability, including without limitation consequential or incidental damages. Typical parameters can and do vary in different applications. All operating parameters must be validated for each customer application by customer's technical experts. CFSensor does not convey any license under its patent rights nor the rights of others.

[CONTACT]

CFSensor

22F/14Bldg High-Tech Park High-Tech Area Wuhu P.R.C.241000 Tel/Fax:+86 18226771331 Email:INFO@CFSensor.com

North America II Europe II Southeast Asia II Middle East II Latin America



IIC Example Code (C51 Language)

```
#include <reg52.h>
#include <stdio.h>
#include <math.h>
#define DELAY TIME 20
#define PMIN 30.0 // The minimum range pressure value for example 20Kpa 传感器最低量程
#define PMAX 110.0 //The full scale pressure value, for example 120Kpa 传感器最大量程
#define DMIN 1677722.0 //AD value corresponding to The minimum range pressure,
                            // for example 10%AD=2^24*0.1 最低量程对应的 AD 值
#define DMAX 15099494.0 //AD Value Corresponding to The full scale pressure value,
                            // for example 90%AD=2^24*0.9 最高量程对应的 AD 值
sbit SCL = P3 \land 3;
                //IIC clock line IIC 时钟线
sbit SDA = P1 \wedge 5;
                   //IIC data line
                                  IIC 数据线
//The 7-bit IIC address of the sensor is 0x78 传感器 7 位 IIC 总线地址
unsigned char Device_Address = 0x78 << 1;
float pressure_kpa = 0.0; //变量, 用于保存压力值, 单位为 KPa
unsigned long pressure_pa = 0; //变量, 用于保存压力值, 单位为 Pa
float temperature = 0.0; //变量, 用于保存温度值, 单位为℃
void Delay_Ms(unsigned char n) //Ms Time-Delay function Ms 延时函数
{
    unsigned char i,j;
    for(i=0;i< n;i++)
         for(j=0;j<123;j++);
}
void Start(void) //Start signal IIC 总线起始信号
{
    SDA = 1;
    Delay_Ms(DELAY_TIME);
    SCL = 1;
    Delay_Ms(DELAY_TIME);
    SDA = 0;
    Delay_Ms(DELAY_TIME);
    SCL = 0:
```



```
Delay_Ms(DELAY_TIME);
}
void Stop(void) //Stop signal IIC 总线停止信号
     SDA = 0;
     Delay_Ms(DELAY_TIME);
     SCL = 1;
     Delay_Ms(DELAY_TIME);
     SDA = 1;
     Delay_Ms(DELAY_TIME);
     SCL = 0;
     Delay_Ms(DELAY_TIME);
}
unsigned char Check_ACK(void) //Read sensor's ACK signal 读取传感器的 ACK 信号
{
     unsigned char ack;
     SDA = 1;
     Delay_Ms(DELAY_TIME);
     SCL = 1;
     Delay_Ms(DELAY_TIME / 2);
     ack = SDA;
     Delay_Ms(DELAY_TIME / 2);
     SCL = 0;
     Delay_Ms(DELAY_TIME);
     return ack;
}
void Send_ACK(void) //Send ACK signal to sensor 向传感器发送 ACK 信号
     SDA = 0;
     Delay_Ms(DELAY_TIME);
     SCL = 1;
     Delay_Ms(DELAY_TIME);
     SCL = 0;
     Delay_Ms(DELAY_TIME);
     SDA = 1;
     Delay_Ms(DELAY_TIME);
}
void SendByte(unsigned char byte1) //Send one byte to sensor 向传感器发送 1 个字节
```



```
unsigned char i = 0;
     do
     {
          if (byte1 & 0x80)
          \{SDA = 1;
          else
          \{SDA = 0; \}
          Delay_Ms(DELAY_TIME);
          SCL = 1;
          Delay_Ms(DELAY_TIME);
          byte1 <<= 1;
          j++;
          SCL = 0;
     ) while (i < 8);
     SCL = 0;
     Delay_Ms(DELAY_TIME);
}
unsigned char ReceiveByte(void) //Receive one byte from sensor 从传感器读取 1 个字节
     unsigned char i = 0, tmp = 0;
     do
     {
          tmp <<= 1;
          SCL = 1;
          Delay_Ms(DELAY_TIME);
          if (SDA)
          \{ tmp |= 1; \}
          SCL = 0;
          Delay_Ms(DELAY_TIME);
          j++;
     ) while (i < 8);
     return tmp;
}
//Write several bytes of data to the sensor 向传感器写若干个字节
unsigned char XGZP6816D_IIC_Write(unsigned char address, unsigned char *buf, unsigned char count)
{
     unsigned char timeout, ack;
     address &= 0xFE; // The lowest bit of address is 0 means writing 地址值最低位为 0 表示写
     Start();
```



```
Delay_Ms(DELAY_TIME);
     SendByte(address);
                          //Send the address to the sensor 向传感器发送地址值
     Delay_Ms(DELAY_TIME);
     timeout = 0;
     do //Getting the ACK response from the sensor means success, otherwise means failure
     { //如能获取传感器的 ACK 信号,则表示 IIC 总线通信成功;否则表示通信失败
         ack = Check_ACK();
         timeout++;
         if (timeout == 10)
              Stop();
              return 1;
         }
    } while (ack);
     while (count)
         SendByte(*buf); //Write bytes to the sensor 向传感器写字节数据
         Delay_Ms(DELAY_TIME);
         timeout = 0;
         do
         {
              ack = Check ACK();
              timeout++;
              if (timeout == 10)
                   return 2;
              }
         } while (0);
         buf++;
         count--;
    Stop();
    return 0;
//Read several bytes of data from the sensor 从传感器读取若干个字节
unsigned char XGZP6816D_IIC_Read(unsigned char address, unsigned char *buf, unsigned char count)
     unsigned char timeout, ack;
     address |= 0x01; // The lowest bit of address is 1 means reading 地址值最低位为 1 表示读
     Start();
     SendByte(address);
```

}



```
Delay_Ms(DELAY_TIME);
    timeout = 0;
    do //Getting the ACK response from the sensor means success, otherwise means failure
    { //如能获取传感器的 ACK 信号,则表示 IIC 总线通信成功;否则表示通信失败
         ack = Check_ACK();
         timeout++;
         if (timeout == 10)
              Stop();
              return 1;
    } while (ack);
    Delay_Ms(DELAY_TIME);
    while (count)
         *buf = ReceiveByte();
         if (count != 1) //Except the last byte, send ACK to the sensor after receiving byte
              Send_ACK(); //除了最后一个字节外, 每接收一个字节, 向传感器发送 ACK 信号
         buf++;
         count--;
    }
    Stop();
    return 0;
}
//Read the status of the sensor and judge whether IIC is busy
unsigned char XGZP6816D_lsBusy(void) //读取传感器的状态变量,用于判断数据是否已准备好被读取
    unsigned char status;
    XGZP6816D_IIC_Read(Device_Address, &status, 1);
    status = (status >> 5) & 0x01;
    return status;
}
void XGZP6816D_get_cal(void) //The function of reading pressure and temperature from the sensor
                                 //从传感器 XGZP6816D 读取压力值和温度值的函数
{
    unsigned char buffer[6] = {0}; //Temp variables used to restoring bytes from the sensor
                                    //临时变量,用于保存从传感器中读出的字节数据
    unsigned long Dtest = 0;
    unsigned int temp_raw = 0;
    buffer[0] = 0xAC; //Send 0xAC command and read the returned six-byte data
```



XGZP6816D IIC Write(Device Address, buffer, 1); //发送 0XAC 命令, 启动一次压力和温度测量

```
Delay_Ms(DELAY_TIME);
     while (1)
    {
         if (XGZP6816D IsBusy()) //判断传感器数据是否已准备好被读取
         {Delay_Ms(DELAY_TIME); }
         else
              break;
     XGZP6816D_IIC_Read(Device_Address, buffer, 6); //读取传感器 6 个字节数据
     //Computing the calibrated pressure and temperature values 计算校准后的压力值和温度值
     Dtest = (unsigned long)((((unsigned long)buffer[1]) << 16) | (((unsigned int)buffer[2]) << 8) | ((unsigned char)buffer[3]));
     temp_raw = ((unsigned int)buffer[4] << 8) | (buffer[5] << 0);
     //The calibrated pressure value is converted into actual values
     if (Dtest != 0)
     { //将校准后的压力值转换成真实的压力值
          pressure_kpa = (float) ((PMAX-PMIN)/(DMAX-DMIN)*(Dtest-DMIN)+PMIN); //单位: KPa
          pressure_pa = (unsigned long) (pressure_kpa * 1000.0); //单位: Pa
    }
     else
          pressure_kpa = 0.0; //pressure value, its unit is KPa 压力值,单位: KPa
          pressure_pa = 0; //pressure value, its unit is Pa 压力值,单位: Pa
     temperature = (float) temp_raw / 65536; //The calibrated temperature value is converted into actual values
     temperature = ((float) temp * 19000 - 4000) / 100; // its unit is °C
                                          //将校准后的温度值转换成真实的温度值,单位: ℃
void main() //The main function
    Printf("CFSensor Ltd");
    while(1)
         XGZP6816D_get_cal();
          Delay_Ms(1000);
         Printf("The pressure from XGZP6816D is %ld Pa\r\n", pressure_pa);
        Printf("The temperature from XGZP6816D is %f CTG\r\n\r\n", temperature);
    }
```

}

{